

Title (en)

DEVICE AND METHOD FOR ELECTROLYTICALLY TREATING ELECTRICALLY INSULATED STRUCTURES

Title (de)

VORRICHTUNG UND VERFAHREN ZUR ELEKTROLYTISCHEN BEHANDLUNG VON ELEKTRISCH ISOLIERTEN STRUKTUREN

Title (fr)

DISPOSITIF ET PROCEDE DE TRAITEMENT PAR VOIE ELECTROLYTIQUE DE STRUCTURES ELECTRIQUEMENT ISOLEES

Publication

EP 1664390 A1 20060607 (EN)

Application

EP 04764415 A 20040819

Priority

- EP 2004009436 W 20040819
- DE 10342512 A 20030912

Abstract (en)

[origin: US2006201817A1] In order to permit continuous electrolytic treatment of small electrically conductive structures that are electrically insulated against each other on electrically insulating foil material, a device for electrolytically treating electrically conductive structures on surfaces of workpiece (1) that are electrically insulated against each other is provided, said device comprising: a) at least one arrangement, comprising at least one electrode (6) for contacting the work pieces (1) and at least one electrolysis region in a respective one of which at least one counter electrode (4) and the work pieces (1) are in contact with the processing liquid, b) the at least one contacting electrode (4) being disposed outside of the at least one electrolysis region and not being in contact with the processing liquid and c) the at least one contacting electrode (6) and that at least one electrolysis region being spaced so close together that small electrically conductive structures can electrolytically be treated.

IPC 1-7

C25D 5/56; C25D 5/06; C25D 7/00; C25D 7/06; C25D 17/10; C25D 17/00

IPC 8 full level

C25D 7/06 (2006.01)

CPC (source: EP KR US)

C25D 7/0621 (2013.01 - EP KR US); **C25D 17/005** (2013.01 - EP KR US)

Citation (search report)

See references of WO 2005026415A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IT LI LU MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

US 2006201817 A1 20060914; AT E350514 T1 20070115; BR PI0413715 A 20061017; BR PI0413715 B1 20130917; CA 2532451 A1 20050324; CN 1849415 A 20061018; DE 10342512 B3 20041028; DE 602004004164 D1 20070215; DE 602004004164 T2 20071011; EP 1664390 A1 20060607; EP 1664390 B1 20070103; HK 1084423 A1 20060728; JP 2007505213 A 20070308; JP 4474414 B2 20100602; KR 101076947 B1 20111026; KR 20060058116 A 20060529; MX PA06002649 A 20060606; TW 200510577 A 20050316; TW I336358 B 20110121; WO 2005026415 A1 20050324

DOCDB simple family (application)

US 56622706 A 20060127; AT 04764415 T 20040819; BR PI0413715 A 20040819; CA 2532451 A 20040819; CN 200480026033 A 20040819; DE 10342512 A 20030912; DE 602004004164 T 20040819; EP 04764415 A 20040819; EP 2004009436 W 20040819; HK 06106798 A 20060614; JP 2006525683 A 20040819; KR 20067003313 A 20040819; MX PA06002649 A 20040819; TW 93126281 A 20040831